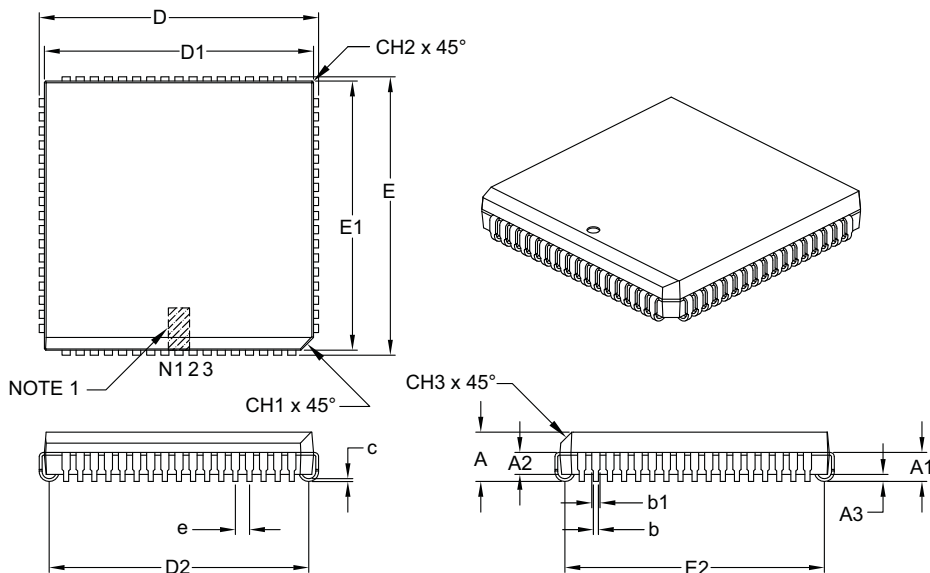


68-Lead Plastic Leaded Chip Carrier (L) – Square [PLCC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	68		
Pitch	e	.050		
Overall Height	A	.165	.172	.180
Contact Height	A1	.090	.105	.120
Molded Package to Contact	A2	.062	–	.083
Standoff §	A3	.020	–	–
Corner Chamfer	CH1	.042	–	.048
Chamfers	CH2	–	–	.020
Side Chamfer	CH3	.042	–	.056
Overall Width	E	.985	.990	.995
Overall Length	D	.985	.990	.995
Molded Package Width	E1	.950	.954	.958
Molded Package Length	D1	.950	.954	.958
Footprint Width	E2	.882	.910	.938
Footprint Length	D2	.882	.910	.938
Lead Thickness	c	.0075	–	.0125
Upper Lead Width	b1	.026	–	.032
Lower Lead Width	b	.013	–	.021

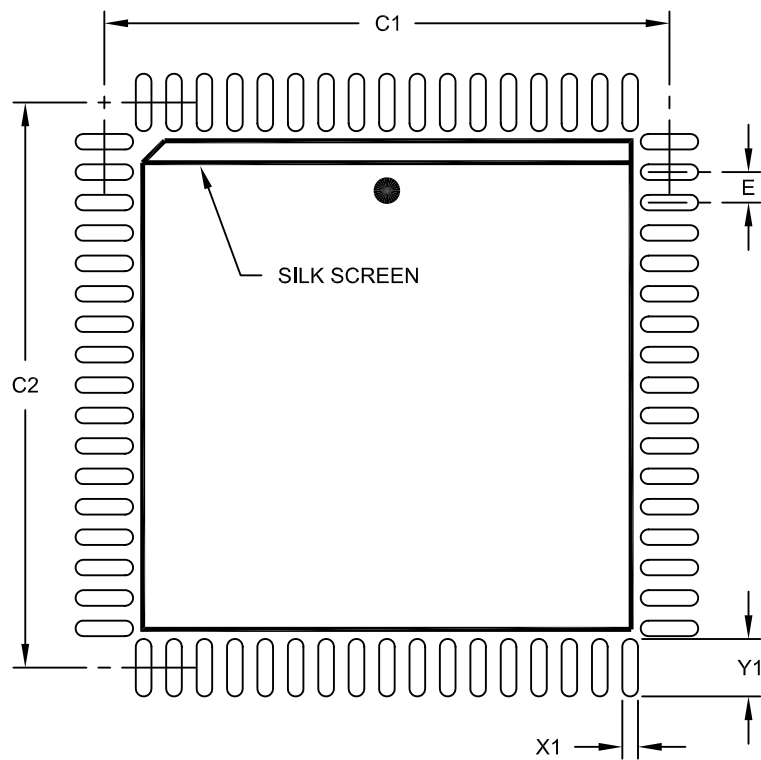
Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

Microchip Technology Drawing C04-049B

68-Lead Plastic Leaded Chip Carrier (LS) - Square [PLCC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	.050 BSC		
Contact Pad Spacing	C1		.929	
Contact Pad Spacing	C2		.929	
Contact Pad Width (X68)	X1			.026
Contact Pad Length (X68)	Y1			.094

Notes:

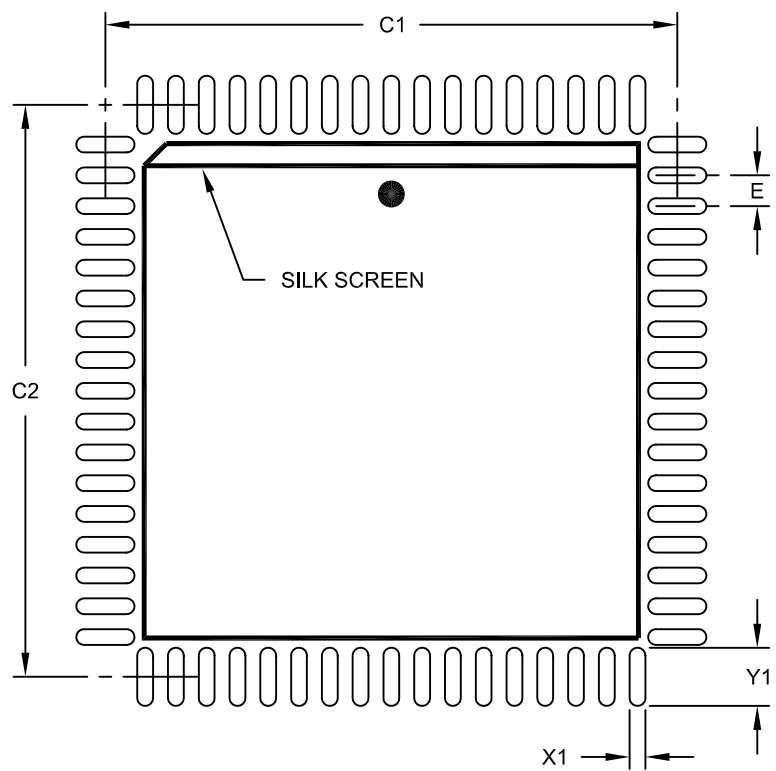
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2049A

68-Lead Plastic Leaded Chip Carrier (LS) - Square [PLCC]

Note: For the most current package drawings, please see the Microchip Packaging Specification at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		INCHES		
Dimension	Limits	MIN	NOM	MAX
Contact Pitch	E	.050 BSC		
Contact Pad Spacing	C1		.929	
Contact Pad Spacing	C2		.929	
Contact Pad Width (X68)	X1			.026
Contact Pad Length (Y68)	Y1			.094